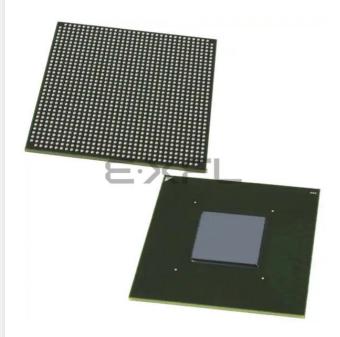
Intel - 5AGXFA7H4F35I3 Datasheet





Welcome to <u>E-XFL.COM</u>

Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	11460
Number of Logic Elements/Cells	242000
Total RAM Bits	15470592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfa7h4f35i3

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Symbol	Description	V _{CCIO} (V)	Value	Unit
		3.0	0.189	
		2.5	0.208	-
		1.8	0.266	-
dR/dT	OCT variation with temperature without recalibration	1.5	0.273	%/°C
		1.35	0.200	
		1.25	0.200	-
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on left/right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN (DC)}	DC current per I/O pin	300	μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8(10)	mA
I _{XCVR-TX (DC)}	DC current per transceiver transmitter (TX) pin	100	mA

Arria V GX, GT, SX, and ST Device Datasheet

Altera Corporation



Sumbol/Decovintion	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
Symbol/Description	Condition	Min	Тур	Max	Min	Тур	Max	Onit
Minimum differential eye opening at the receiver serial input pins ⁽³⁰⁾	_	100	_	_	100	_	_	mV
V _{ICM} (AC coupled)	_	_	0.7/0.75/ 0.8 ⁽³¹⁾	_	_	0.7/0.75/ 0.8 ⁽³¹⁾		mV
V _{ICM} (DC coupled)	$\leq 3.2 \text{Gbps}^{(32)}$	670	700	730	670	700	730	mV
	85- Ω setting		85	—	_	85	_	Ω
Differential on-chip	100- Ω setting		100	_		100		Ω
termination resistors	120-Ω setting		120	—		120		Ω
	150-Ω setting		150	_		150		Ω
t _{LTR} ⁽³³⁾		_	_	10	_	_	10	μs
$t_{LTD}^{(34)}$	_	4	_	_	4	_	_	μs
t _{LTD_manual} ⁽³⁵⁾	_	4	_	—	4	_	_	μs
t _{LTR_LTD_manual} ⁽³⁶⁾		15	_		15			μs
Programmable ppm detector ⁽³⁷⁾	_		±62.5, 100, 125, 200, 250, 300, 500, and 1000				ppm	

⁽³⁰⁾ The differential eye opening specification at the receiver input pins assumes that you have disabled the **Receiver Equalization** feature. If you enable the **Receiver Equalization** feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(31) The AC coupled $V_{ICM} = 700 \text{ mV}$ for Arria V GX and SX in PCIe mode only. The AC coupled $V_{ICM} = 750 \text{ mV}$ for Arria V GT and ST in PCIe mode only.

⁽³²⁾ For standard protocol compliance, use AC coupling.

 $^{(33)}$ t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

 $^{(34)}$ t_{LTD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.

 $^{(35)}$ t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.

 $t_{\text{LTR_LTD_manual}}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.



Sumbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
Symbol/Description	Condition	Min	Тур	Max	Min	Тур	Max	Unit
Inter-transceiver block transmitter channel-to- channel skew ⁽³⁹⁾	×N PMA bonded mode	_	_	500	_	_	500	ps

Table 1-24: CMU PLL Specifications for Arria V GX and SX Devices

Symbol/Description	Transceiver Speed Grade 4		Transceiver S	peed Grade 6	Unit	
Symbol/Description	Min	Мах	Min	Мах	Onit	
Supported data range	611	6553.6	611	3125	Mbps	
fPLL supported data range	611	3125	611	3125	Mbps	

Table 1-25: Transceiver-FPGA Fabric Interface Specifications for Arria V GX and SX Devices

Symbol/Description	Transceiver Spee	ed Grade 4 and 6	Unit	
Symbol/Description	Min	Мах	Unit	
Interface speed (single-width mode)	25	187.5	MHz	
Interface speed (double-width mode)	25	163.84	MHz	

Related Information

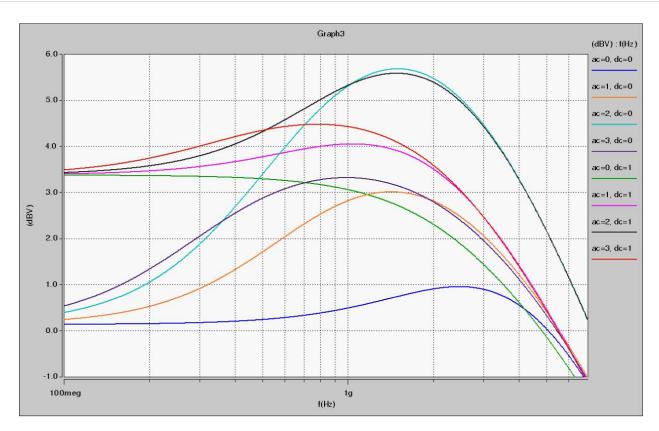
- CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain on page 1-35
- CTLE Response at Data Rates \leq 3.25 Gbps across Supported AC Gain and DC Gain on page 1-36
- Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines Provides more information about the power supply connection for different data rates.



⁽³⁹⁾ This specification is only applicable to channels on one side of the device across two transceiver banks.

CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain

Figure 1-3: CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain for Arria V GX, GT, SX, and ST Devices





Symbol	Parameter	Condition	Min	Тур	Мах	Unit
t (67)(71)	Period jitter for dedicated clock output	$F_{OUT} \ge 100 \text{ MHz}$	_		175	ps (p-p)
t _{CASC_OUTPJ_DC} ⁽⁶⁷⁾⁽⁷¹⁾	in cascaded PLLs	F _{OUT} < 100 MHz	_		17.5	mUI (p-p)
t _{DRIFT}	Frequency drift after PFDENA is disabled for a duration of 100 μs		_	_	±10	%
dK _{BIT}	Bit number of Delta Sigma Modulator (DSM)	_	8	24	32	bits
k _{VALUE}	Numerator of fraction		128	8388608	2147483648	
f _{RES}	Resolution of VCO frequency	$f_{INPFD} = 100 \text{ MHz}$	390625	5.96	0.023	Hz

Related Information

Memory Output Clock Jitter Specifications on page 1-57

Provides more information about the external memory interface clock output jitter specifications.

- Upstream PLL: 0.59 MHz ≤ Upstream PLL BW < 1 MHz
- Downstream PLL: Downstream PLL BW > 2 MHz



⁽⁷¹⁾ The cascaded PLL specification is only applicable with the following conditions:

HPS Clock Performance

Table 1-48: HPS Clock Performance for Arria V Devices

Symbol/Description	-I3	-C4	–C5, –I5	-C6	Unit
mpu_base_clk (microprocessor unit clock)	1050	925	800	700	MHz
main_base_clk (L3/L4 interconnect clock)	400	400	400	350	MHz
h2f_user0_clk	100	100	100	100	MHz
h2f_user1_clk	100	100	100	100	MHz
h2f_user2_clk	200	200	200	160	MHz

HPS PLL Specifications

HPS PLL VCO Frequency Range

Table 1-49: HPS PLL VCO Frequency Range for Arria V Devices

Description	Speed Grade	Minimum	Maximum	Unit
	-C5, -I5, -C6	320	1,600	MHz
VCO range	-C4	320	1,850	MHz
	-I3	320	2,100	MHz

HPS PLL Input Clock Range

The HPS PLL input clock range is 10 – 50 MHz. This clock range applies to both HPS_CLK1 and HPS_CLK2 inputs.

Related Information

Clock Select, Booting and Configuration chapter

Provides more information about the clock range for different values of clock select (CSEL).



HPS PLL Input Jitter

Use the following equation to determine the maximum input jitter (peak-to-peak) the HPS PLLs can tolerate. The divide value (N) is the value programmed into the denominator field of the VCO register for each PLL. The PLL input reference clock is divided by this value. The range of the denominator is 1 to 64.

Maximum input jitter = Input clock period × Divide value (N) × 0.02

Table 1-50: Examples of Maximum Input Jitter

Input Reference Clock Period	Divide Value (N)	Maximum Jitter	Unit
40 ns	1	0.8	ns
40 ns	2	1.6	ns
40 ns	4	3.2	ns

Quad SPI Flash Timing Characteristics

Table 1-51: Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Arria V Devices

Symbol	Description	Min	Тур	Мах	Unit
F _{clk}	SCLK_OUT clock frequency (External clock)	—	_	108	MHz
T _{qspi_clk}	QSPI_CLK clock period (Internal reference clock)	2.32	_		ns
T _{dutycycle}	SCLK_OUT duty cycle	45		55	%
T _{dssfrst}	Output delay QSPI_SS valid before first clock edge		1/2 cycle of SCLK_OUT		ns
T _{dsslst}	Output delay QSPI_SS valid after last clock edge	-1		1	ns
T _{dio}	I/O data output delay	-1		1	ns
T _{din_start}	Input data valid start			$(2 + R_{delay}) \times T_{qspi_clk} - 7.52^{(85)}$	ns



Figure 1-12: USB Timing Diagram



Ethernet Media Access Controller (EMAC) Timing Characteristics

Table 1-56: Reduced Gigabit Media Independent Interface (RGMII) TX Timing Requirements for Arria V Devices

Symbol	Description	Min	Тур	Max	Unit
T _{clk} (1000Base-T)	TX_CLK clock period	_	8	_	ns
T _{clk} (100Base-T)	TX_CLK clock period	—	40		ns
T _{clk} (10Base-T)	TX_CLK clock period	_	400		ns
T _{dutycycle}	TX_CLK duty cycle	45		55	%
T _d	TX_CLK to TXD/TX_CTL output data delay	-0.85		0.15	ns

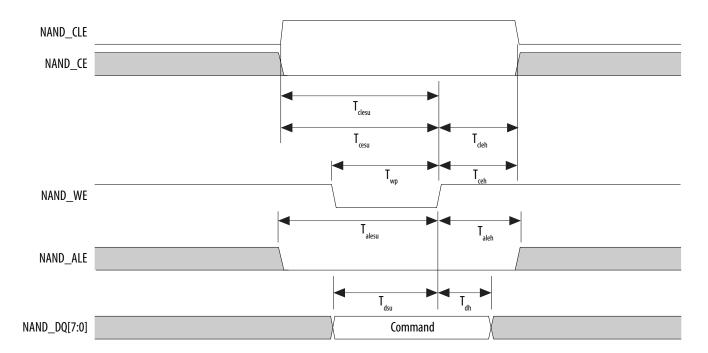
Figure 1-13: RGMII TX Timing Diagram





Symbol	Description	Min	Мах	Unit
T _{dh} ⁽⁸⁹⁾	Data to write enable hold time	5	—	ns
T _{cea}	Chip enable to data access time		25	ns
T _{rea}	Read enable to data access time		16	ns
T _{rhz}	Read enable to data high impedance		100	ns
T _{rr}	Ready to read enable low	20		ns

Figure 1-17: NAND Command Latch Timing Diagram





Related Information

- PS Configuration Timing on page 1-81
- AS Configuration Timing

Provides the AS configuration timing waveform.

DCLK Frequency Specification in the AS Configuration Scheme

Table 1-69: DCLK Frequency Specification in the AS Configuration Scheme

This table lists the internal clock frequency specification for the AS configuration scheme. The DCLK frequency specification applies when you use the internal oscillator as the configuration clock source. The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Parameter	Minimum	Typical	Maximum	Unit
	5.3	7.9	12.5	MHz
DCLK frequency in AS configuration scheme	10.6	15.7	25.0	MHz
Bellk frequency in AS configuration scheme	21.3	31.4	50.0	MHz
	42.6	62.9	100.0	MHz

PS Configuration Timing

Table 1-70: PS Timing Parameters for Arria V Devices

Symbol	Parameter	Minimum	Maximum	Unit
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nCONFIG low to nSTATUS low		600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μs
t _{STATUS}	nSTATUS low pulse width	268	1506 ⁽¹⁰³⁾	μs
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1506(104)	μs

 $^{^{(103)}\,}$ You can obtain this value if you do not delay configuration by extending the <code>nCONFIG</code> or <code>nSTATUS</code> low pulse width.



⁽¹⁰⁴⁾ You can obtain this value if you do not delay configuration by externally holding nSTATUS low.

Remote System Upgrades

Table 1-74: Remote System Upgrade Circuitry Timing Specifications for Arria V Devices

Parameter	Minimum	Unit		
t _{RU_nCONFIG} ⁽¹¹⁰⁾	250	ns		
t _{RU_nRSTIMER} ⁽¹¹¹⁾	250	ns		

Related Information

- **Remote System Upgrade State Machine** Provides more information about configuration reset (RU_CONFIG) signal.
- User Watchdog Timer Provides more information about reset_timer (RU_nRSTIMER) signal.

User Watchdog Internal Oscillator Frequency Specifications

Table 1-75: User Watchdog Internal Oscillator Frequency Specifications for Arria V Devices

Parameter	Minimum	Typical	Maximum	Unit	
User watchdog internal oscillator frequency	5.3	7.9	12.5	MHz	

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O timing and the Quartus Prime Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis.





⁽¹¹⁰⁾ This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification.

⁽¹¹¹⁾ This is equivalent to strobing the reset timer input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification.

2-4 Recommended Operating Conditions

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% of the duty cycle.

For example, a signal that overshoots to 3.95 V can be at 3.95 V for only $\sim 21\%$ over the lifetime of the device; for a device lifetime of 10 years, the overshoot duration amounts to ~ 2 years.

Table 2-4: Maximum Allowed Overshoot During Transitions for Arria V GZ Devices
--

Symbol	Description	Condition (V)	Overshoot Duration as $\% @ T_J = 100^{\circ}C$	Unit
		3.8	100	%
		3.85	64	%
		3.9	36	%
		3.95	21	%
Vi (AC)	AC input voltage	4	12	%
		4.05	7	%
		4.1	4	%
		4.15	2	%
		4.2	1	%

Recommended Operating Conditions

Table 2-5: Recommended Operating Conditions for Arria V GZ Devices

Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V _{CC}	Core voltage and periphery circuitry power supply (115)	_	0.82	0.85	0.88	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.





⁽¹¹⁵⁾ The V_{CC} core supply must be set to 0.9 V if the Partial Reconfiguration (PR) feature is used.

Symbol	Description	Condition	Minimum ⁽¹¹⁴⁾	Typical	Maximum ⁽¹¹⁴⁾	Unit
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V _{CCPD} ⁽¹¹⁶	technology		2.85	3.0	3.15	V
)			2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85		3.15	V
	I/O buffers (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply		1.71	1.8	1.89	V
V _{CCIO}	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply	_	1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply	_	1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply	_	2.85	3.0	3.15	V
V _{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA} _	PLL analog voltage regulator power supply	_	2.375	2.5	2.625	V
V _{CCD} FPLL	PLL digital voltage regulator power supply	_	1.45	1.5	1.55	V
V _{CCBAT} (117	Battery back-up power supply (For design security volatile key register)	_	1.2	—	3.0	V

⁽¹¹⁴⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements.
Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.



⁽¹¹⁶⁾ V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.

⁽¹¹⁷⁾ If you do not use the design security feature in Arria V GZ devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Arria V GZ power-on-reset (POR) circuitry monitors V_{CCBAT}. Arria V GZ devices do not exit POR if V_{CCBAT} is not powered up.

Bus Hold Specifications

Table 2-9: Bus Hold Parameters for Arria V GZ Devices

			V _{ccio}										
Parameter	Symbol	Conditions	1.2	2 V	1.5	5 V	1.8	8 V	2.5	5 V	3.() V	Unit
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5		25.0	_	30.0	_	50.0		70.0		μΑ
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	-22.5		-25.0		-30.0	_	-50.0		-70.0	_	μΑ
Low overdrive current	I _{ODL}	$\begin{array}{c} 0\mathrm{V} < \mathrm{V_{IN}} < \\ \mathrm{V_{CCIO}} \end{array}$		120	_	160		200		300	_	500	μA
High overdrive current	I _{ODH}	$0V < V_{IN} < V_{CCIO}$		-120		-160	_	-200		-300	_	-500	μΑ
Bus-hold trip point	V _{TRIP}	_	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block.

Table 2-10: OCT Calibration Accuracy Specifications for Arria V GZ Devices

OCT calibration accuracy is valid at the time of calibration only.





Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.0297	
		2.5	0.0344	
dR/dV	OCT variation with voltage without re-calibration	1.8	0.0499	%/mV
		1.5	0.0744	
		1.2	0.1241	
		3.0	0.189	
		2.5	0.208	
dR/dT	OCT variation with temperature without re-calibration	1.8	0.266	%/°C
		1.5	0.273	
		1.2	0.317	

Pin Capacitance

Table 2-13: Pin Capacitance for Arria V GZ Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF



I/O Standard Specifications

The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.

Table 2-16: Single-Ended I/O Standards for Arria V GZ Devices

I/O Standard		V _{CCIO} (V)		VII	_ (V)	V _{IH}	(V)	V _{OL} (V)	V _{OH} (V)	l _{OL} (mA)	l _{OH} (mA)
	Min	Тур	Max	Min	Max	Min	Max	Max	Min	10L (IIIA)	10H (1117)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} – 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	$0.35 \times V_{ m CCIO}$	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} - 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	$0.35 \times V_{ m CCIO}$	0.65 × V _{CCIO}	V _{CCIO} + 0.3	$0.25 imes V_{ m CCIO}$	$0.75 \times V_{CCIO}$	2	-2
1.2 V	1.14	1.2	1.26	-0.3	$0.35 \times V_{ m CCIO}$	0.65 × V _{CCIO}	V _{CCIO} + 0.3	0.25 × V _{CCIO}	$0.75 \times V_{CCIO}$	2	-2

Table 2-17: Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Arria V GZ Devices

I/O Standard		V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)			
	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max		
SSTL-2 Class I, II	2.375	2.5	2.625	$0.49 \times V_{CCIO}$	$0.5 imes V_{ m CCIO}$	$0.51 \times V_{ m CCIO}$	V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04		
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} - 0.04	V _{REF}	V _{REF} + 0.04		
SSTL-15 Class I, II	1.425	1.5	1.575	$0.49 \times V_{CCIO}$	$0.5 imes V_{ m CCIO}$	$0.51 \times V_{ m CCIO}$	$0.49 \times V_{\rm CCIO}$	0.5 × VCCIO	$0.51 \times V_{CCIO}$		



Memory	Mode	Resou	rces Used		Unit			
Memory	imoue	ALUTs	Memory	C3	C4	I3L	14	
	Single-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port, all supported widths	0	1	650	550	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	455	400	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512×32	0	1	400	350	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	500	450	500	450	MHz
	True dual port, all supported widths	0	1	650	550	500	450	MHz
	ROM, all supported widths	0	1	650	550	500	450	MHz

Temperature Sensing Diode Specifications

Table 2-37: Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°C to 100°C	±8°C	No	1 MHz, 500 kHz	< 100 ms	8 bits	8 bits

Table 2-38: External Temperature Sensing Diode Specifications for Arria V GZ Devices

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	—	200	μΑ
V _{bias,} voltage across diode	0.3	_	0.9	V
Series resistance			< 1	Ω



AV-51002 2017.02.10

Symbol	Conditions	C3, I3L				Unit			
Symbol	Conditions	Min	Тур	Мах	Min	Тур	Мах		
t _{x Jitter} - True Differential I/O	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	ps	
Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_		0.1	UI	
t _{x Jitter} - Emulated Differential I/O Standards with Three	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	_	300	_		325	ps	
External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_		0.25	UI	
t _{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	%	
	True Differential I/O Standards		_	200			200	ps	
t _{RISE} & t _{FALL}	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	300	ps	
	True Differential I/O Standards		_	150			150	ps	
TCCS	Emulated Differential I/O Standards		—	300			300	ps	

Receiver High-Speed I/O Specifications

Table 2-41: Receiver High-Speed I/O Specifications for Arria V GZ Devices

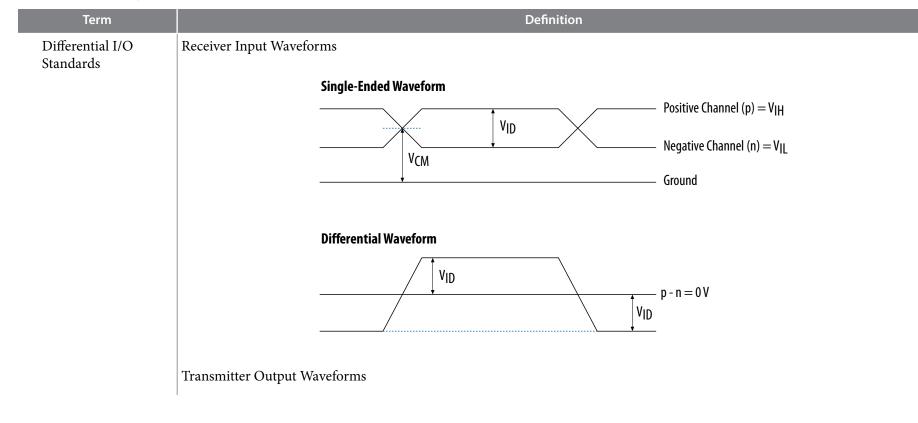
When J = 3 to 10, use the serializer/deserializer (SERDES) block.

When J = 1 or 2, bypass the SERDES block.



Glossary

Table 2-68: Glossary





Term	Definition
V _{OCM}	Output common mode voltage—The common mode of the differential signal at the transmitter.
V _{OD}	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
V _{SWING}	Differential input voltage
V _X	Input differential cross point voltage
V _{OX}	Output differential cross point voltage
W	High-speed I/O block—clock boost factor

Document Revision History

Date	Version	Changes
February 2017	2017.02.10	• Changed the minimum value for t _{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is 1" table.
		 Changed the minimum value for t_{CD2UMC} in the "FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1" table.
		• Changed the minimum value for t _{CD2UMC} in the "AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices" table.
		• Changed the minimum value for t _{CD2UMC} in the "PS Timing Parameters for Arria V GZ Devices" table.
		 Changed the minimum number of clock cycles value in the "Initialization Clock Source Option and the Maximum Frequency for Arria V GZ Devices" table.

